

## Product summary

| $V_{DS}$ (V) | $R_{DS(on),max}$ (m $\Omega$ ) | $I_D$ (A)         |
|--------------|--------------------------------|-------------------|
| 100          | 12 @ $V_{GS} = 10V$            | 43 <sup>(1)</sup> |

## Features

- Low  $R_{DS(on)}$  SGT technology
- Low thermal impedance
- Fast switching speed
- 100% avalanche tested.

## Applications

- DC/DC conversion
- Power switch
- Motor drives

## 1. Maximum ratings

| Absolute maximum ratings ( $T_A = 25^\circ\text{C}$ unless otherwise noted) |                                         |                |            |                  |
|-----------------------------------------------------------------------------|-----------------------------------------|----------------|------------|------------------|
| Parameter                                                                   |                                         | Symbol         | Limit      | Unit             |
| Drain-source voltage                                                        |                                         | $V_{DS}$       | 100        | V                |
| Gate-source voltage                                                         |                                         | $V_{GS}$       | $\pm 20$   |                  |
| Continuous drain current                                                    | $T_C = 25^\circ\text{C}$ <sup>(1)</sup> | $I_D$          | 43         | A                |
|                                                                             | $T_C = 100^\circ\text{C}$               |                | 27         |                  |
|                                                                             | $T_A = 25^\circ\text{C}$ <sup>(4)</sup> |                | 11         |                  |
| Pulsed drain current <sup>(2)</sup>                                         |                                         | $I_{D,pulse}$  | 172        |                  |
| Avalanche energy, single pulse <sup>(3)</sup>                               |                                         | $E_{AS}$       | 31         | mJ               |
| Power dissipation                                                           | $T_C = 25^\circ\text{C}$                | $P_D$          | 43.1       | W                |
|                                                                             | $T_A = 25^\circ\text{C}$ <sup>(4)</sup> |                | 2.7        |                  |
| Operating junction and storage temperature range                            |                                         | $T_J, T_{stg}$ | -55 to 150 | $^\circ\text{C}$ |

## 2. Thermal resistance ratings

| Thermal resistance ratings                             |              |                 |      |      |  |  |
|--------------------------------------------------------|--------------|-----------------|------|------|--|--|
| Parameter                                              |              | Symbol          | Max. | Unit |  |  |
| Thermal resistance, junction-to-case                   | Steady state | $R_{\theta JC}$ | 2.9  | °C/W |  |  |
| Thermal resistance, junction-to-ambient <sup>(4)</sup> | Steady state | $R_{\theta JA}$ | 45   |      |  |  |

## 3. Electrical Characteristics

| Electrical characteristics                   |                      |                                                                                                   |      |      |      |      |
|----------------------------------------------|----------------------|---------------------------------------------------------------------------------------------------|------|------|------|------|
| Parameter                                    | Symbol               | Test conditions                                                                                   | Min. | Typ. | Max. | Unit |
| Static parameter                             |                      |                                                                                                   |      |      |      |      |
| Drain to source breakdown voltage            | V <sub>(BR)DSS</sub> | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA                                                    | 100  |      |      | V    |
| Gate-source threshold voltage                | V <sub>GS(th)</sub>  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA                                       | 1.1  | 1.8  | 2.5  | V    |
| Gate-body leakage                            | I <sub>GSS</sub>     | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V                                                    |      |      | ±100 | nA   |
| Zero gate voltage drain current              | I <sub>DSS</sub>     | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V                                                    |      |      | 1    | μA   |
| Drain-source on-resistance                   | R <sub>DS(on)</sub>  | V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A                                                    |      | 13.6 | 18   | mΩ   |
|                                              |                      | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A                                                     |      | 9.2  | 12   |      |
| Forward transconductance <sup>(5)</sup>      | g <sub>fs</sub>      | V <sub>DS</sub> = 5 V, I <sub>D</sub> = 10 A                                                      |      | 23   |      | S    |
| Gate resistance                              | R <sub>g</sub>       | f = 1 MHz                                                                                         |      | 1.6  |      | Ω    |
| Dynamic <sup>(5)</sup>                       |                      |                                                                                                   |      |      |      |      |
| Total gate charge                            | Q <sub>g</sub>       | V <sub>DS</sub> = 50 V, I <sub>D</sub> = 10 A, V <sub>GS</sub> = 10 V                             |      | 31   |      | nC   |
| Total gate charge                            | Q <sub>g</sub>       | V <sub>DS</sub> = 50V, I <sub>D</sub> = 10 A, V <sub>GS</sub> = 4.5 V                             |      | 17.2 |      |      |
| Gate-source charge                           | Q <sub>gs</sub>      |                                                                                                   |      | 4.3  |      |      |
| Gate-drain charge                            | Q <sub>gd</sub>      |                                                                                                   |      | 9.4  |      |      |
| Turn-on delay time                           | t <sub>d(on)</sub>   | V <sub>DS</sub> = 50V, I <sub>D</sub> = 10 A, V <sub>GS</sub> = 10 V,<br>R <sub>GEN</sub> = 4.7 Ω |      | 7    |      | ns   |
| Rise time                                    | t <sub>r</sub>       |                                                                                                   |      | 17   |      |      |
| Turn-off delay time                          | t <sub>d(off)</sub>  |                                                                                                   |      | 28   |      |      |
| Fall time                                    | t <sub>f</sub>       |                                                                                                   |      | 27   |      |      |
| Input capacitance                            | C <sub>iss</sub>     | V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1 MHz                                          |      | 1470 |      | pF   |
| Output capacitance                           | C <sub>oss</sub>     |                                                                                                   |      | 230  |      |      |
| Reverse transfer capacitance                 | C <sub>rss</sub>     |                                                                                                   |      | 11   |      |      |
| Reverse Diode Characteristics <sup>(5)</sup> |                      |                                                                                                   |      |      |      |      |
| Diode forward voltage                        | V <sub>SD</sub>      | V <sub>GS</sub> = 0 V, I <sub>F</sub> = 10 A                                                      |      | 0.8  | 1.1  | V    |
| Reverse recovery time                        | t <sub>rr</sub>      | V <sub>DS</sub> = 50 V, I <sub>F</sub> = 10 A, di/dt = 100 A/μs                                   |      | 41   |      | ns   |
| Reverse recovery charge                      | Q <sub>rr</sub>      |                                                                                                   |      | 44   |      | nC   |

### Notes

- (1) Limited by maximum junction temperature.
- (2) Pulse width limited by maximum junction temperature.
- (3)  $V_{DS} = 50\text{ V}, V_{GS} = 10\text{ V}, L = 0.1\text{ mH}$ .
- (4)  $R_{\theta JA}$  is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5x1.5 in. board of FR-4 material.
- (5) Guaranteed by design, not subject to production testing.

### 4. Electrical characteristics diagrams

Fig.1 Typ. transfer characteristics

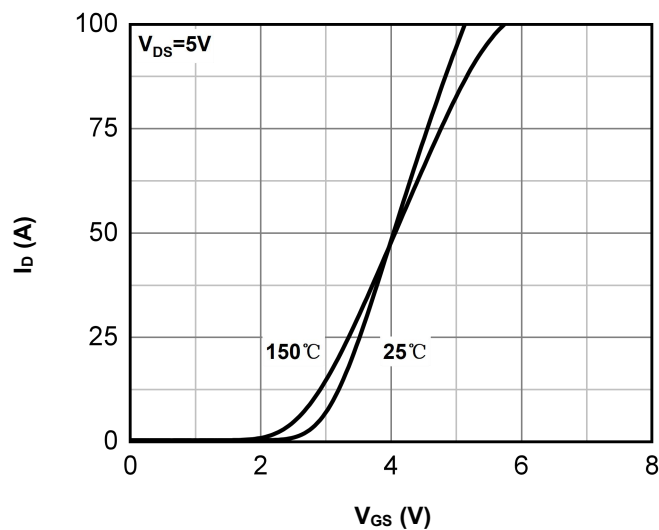


Fig.2 Typ. output characteristics

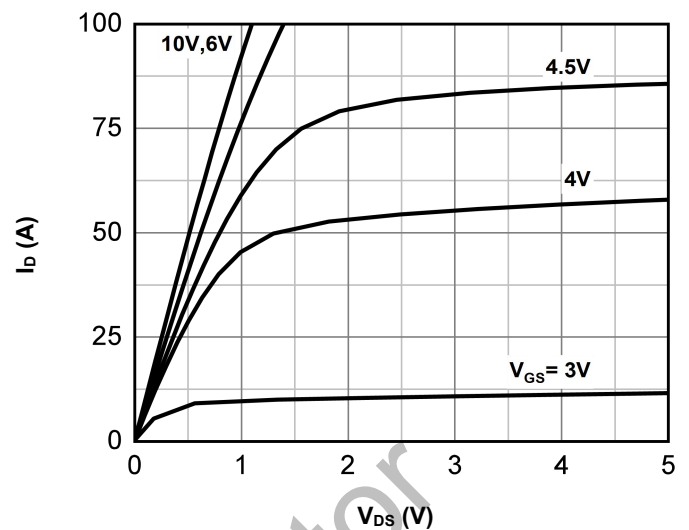


Fig.3 Normalized on-resistance vs drain current

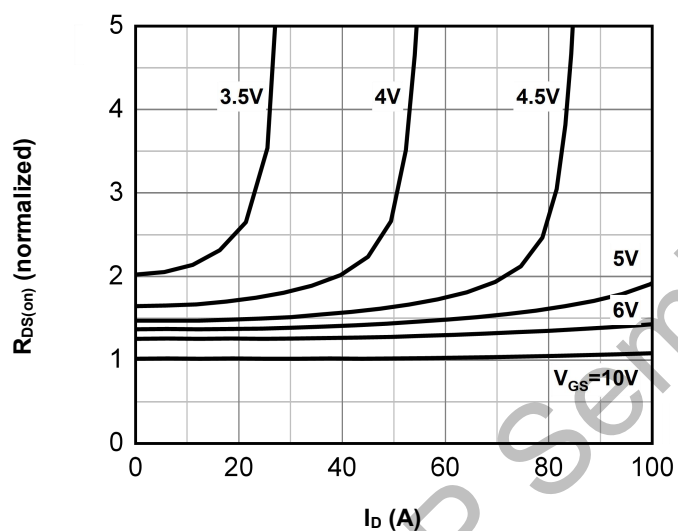


Fig.4 Typ. on-resistance vs gate-source voltage

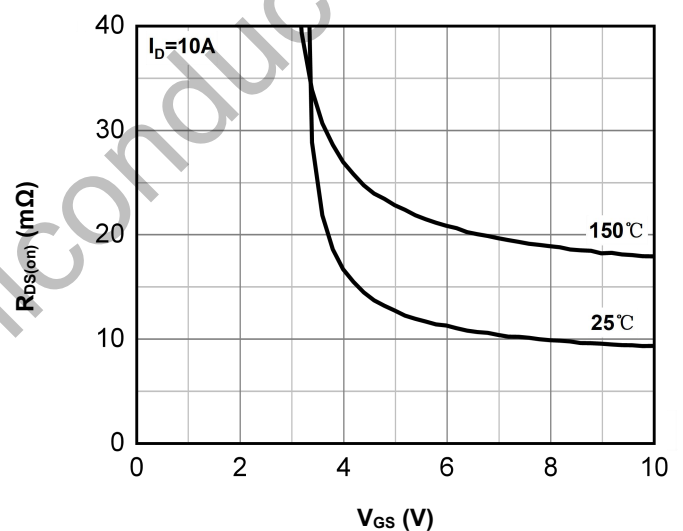


Fig.5 Normalized on-resistance vs junction temperature

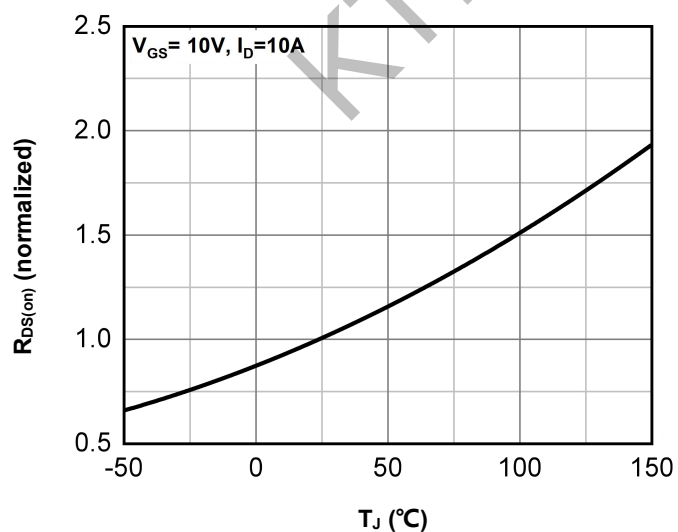


Fig.6 Typ. gate charge

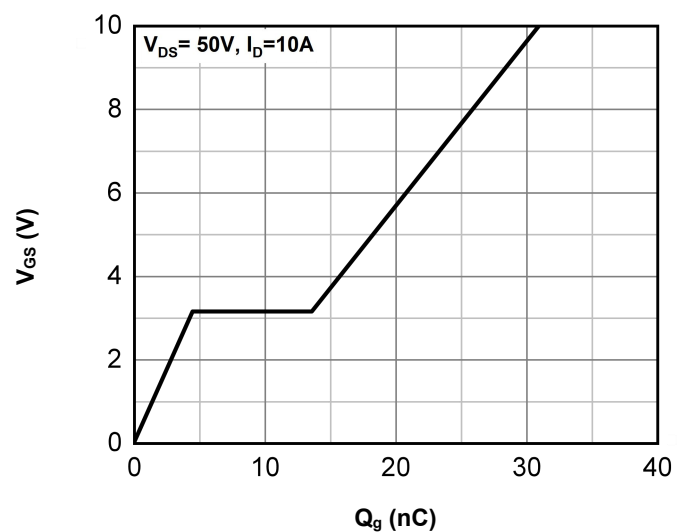


Fig.7 Typ. forward characteristics of body diode

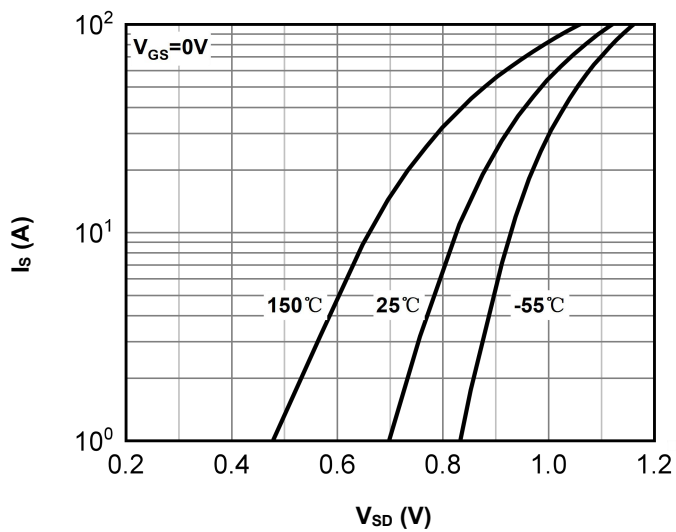


Fig.8 Safe operating area

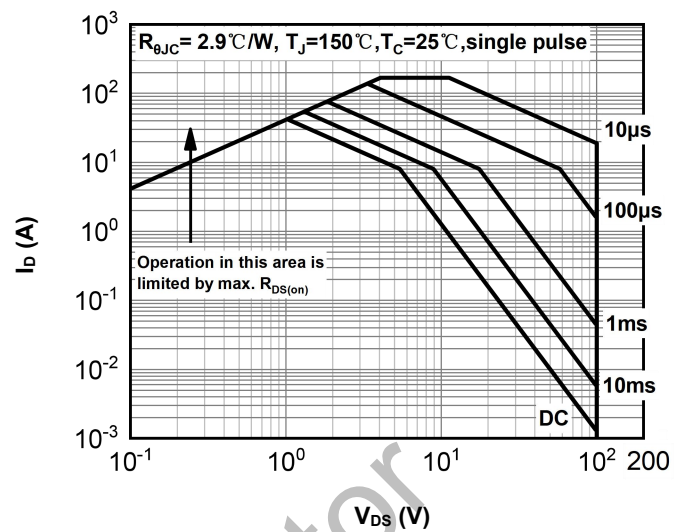


Fig.9 Typ. Capacitance

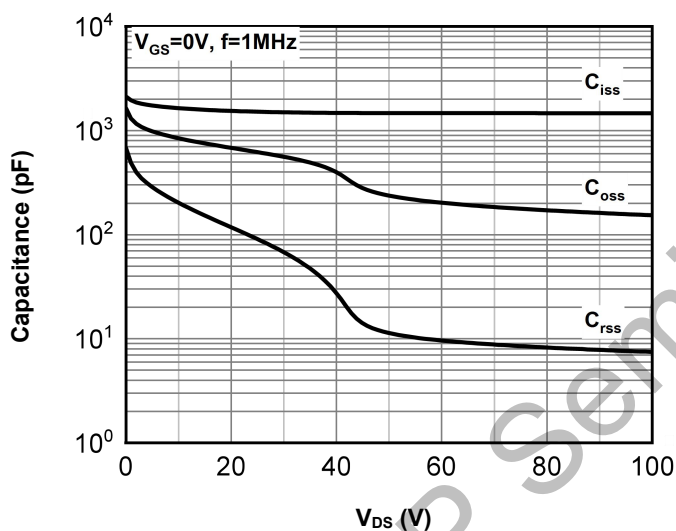


Fig.10 Single pulse maximum power dissipation

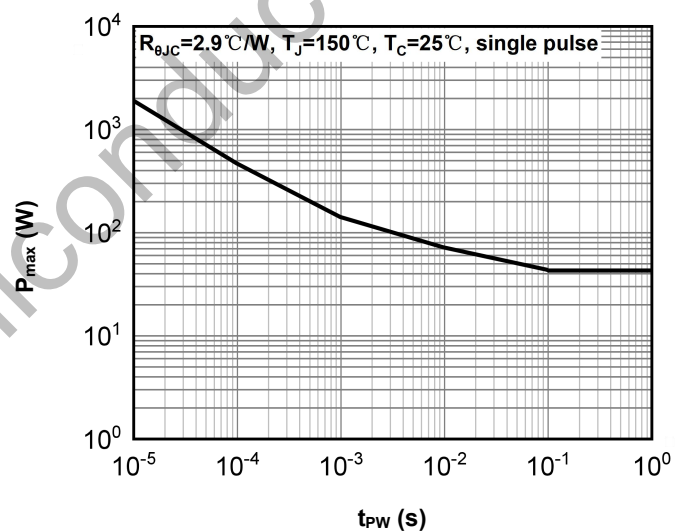


Fig.11 Max. power dissipation vs case temperature

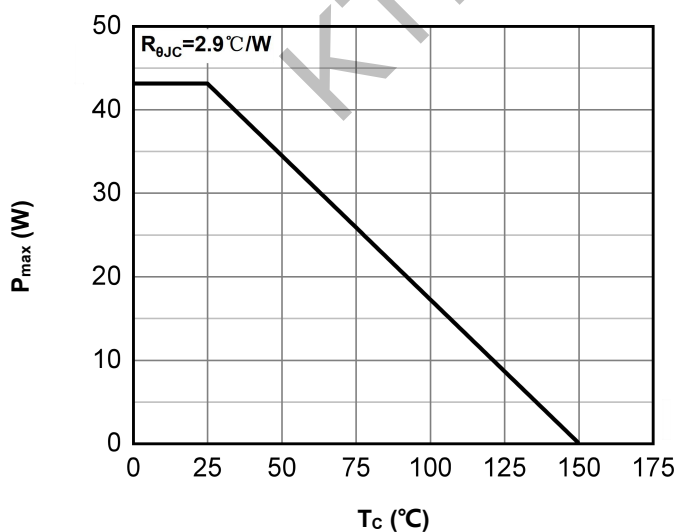


Fig.12 Max. continuous drain current vs case temperature

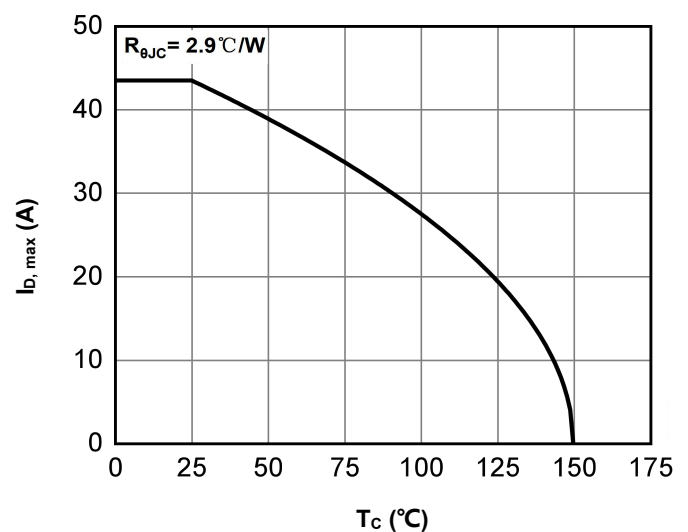


Fig.13 Normalized  $V_{(BR)DSS}$  vs junction temperature

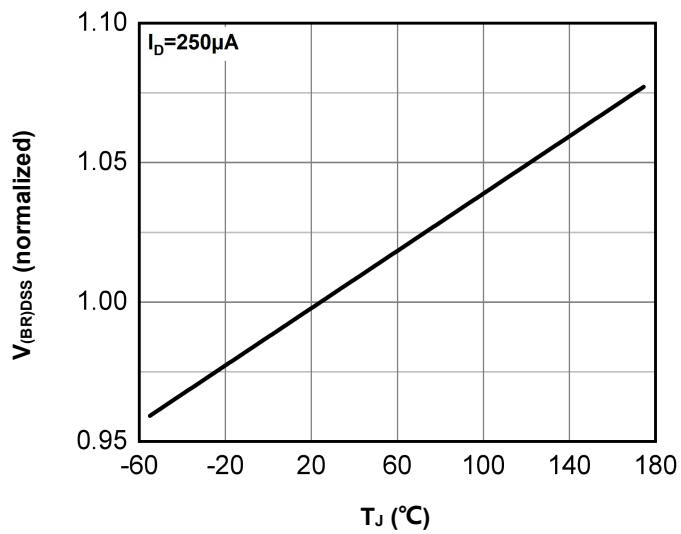


Fig.14 Normalized  $V_{GS(th)}$  vs junction temperature

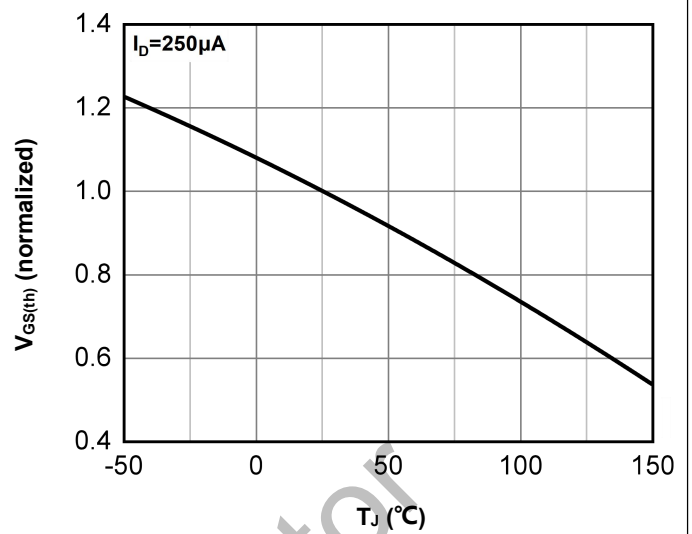
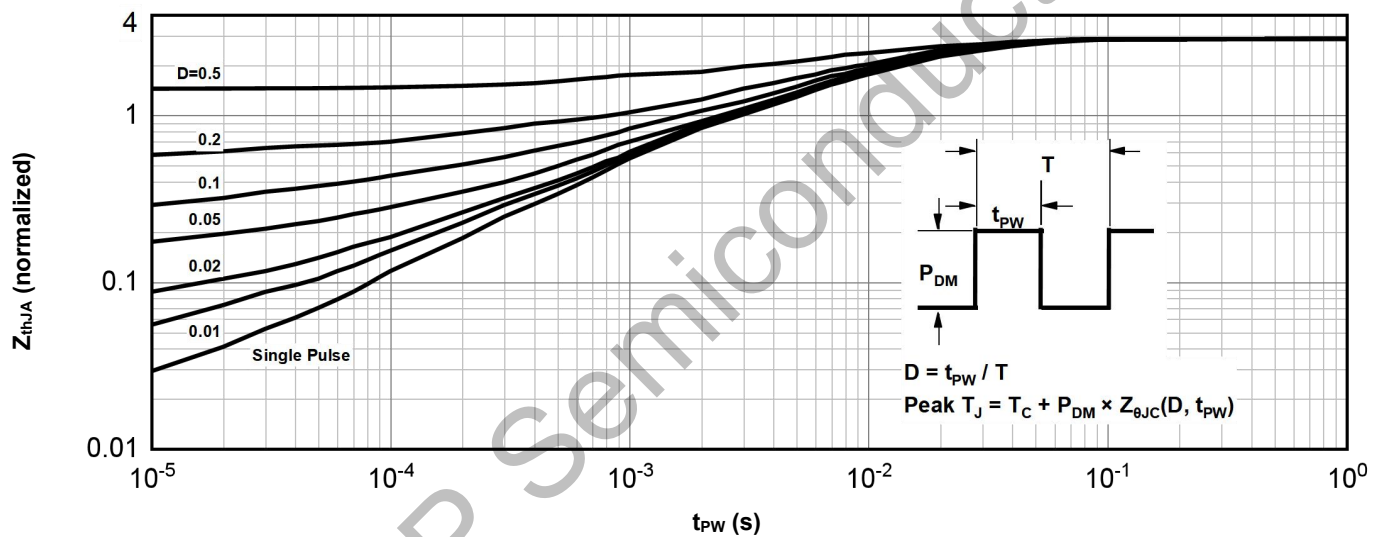
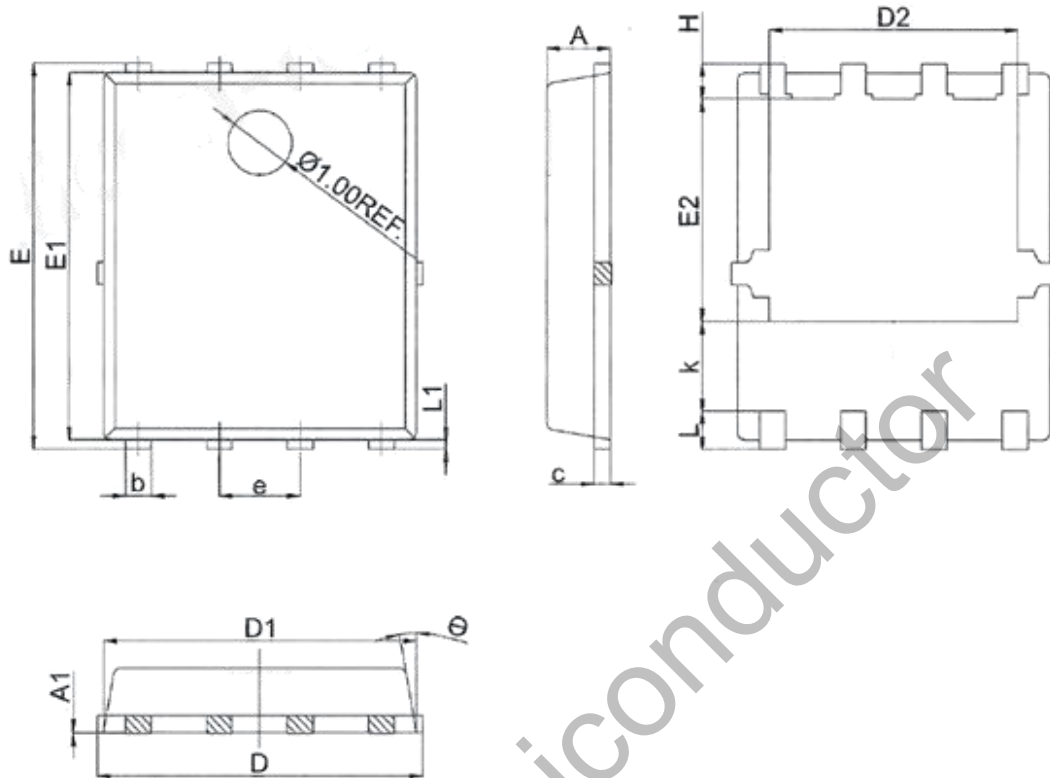


Fig.15 Normalized transient thermal impedance from junction to ambient



## 5. Package outline dimensions

PDFN5\*6



| Dim | Millimeters |      |       |
|-----|-------------|------|-------|
|     | Min         | Nom  | Max   |
| A   | 0.90        | 1.00 | 1.10  |
| A1  | —           | —    | 0.05  |
| b   | 0.30        | 0.40 | 0.50  |
| c   | 0.20        | 0.25 | 0.30  |
| D   | 4.80        | 5.10 | 5.40  |
| D1  | 4.80        | 4.90 | 5.00  |
| D2  | 3.75        | 3.90 | 4.11  |
| E   | 5.95        | 6.05 | 6.15  |
| E1  | 5.65        | 5.75 | 5.85  |
| E2  | 3.34        | 3.49 | 3.64  |
| e   | 1.27 BSC    |      |       |
| H   | 0.46        | 0.56 | 0.726 |
| k   | 1.10        | —    | —     |
| L   | 0.51        | 0.61 | 0.71  |
| L1  | 0.05        | 0.15 | 0.25  |
| Θ   | 8°          | 10°  | 12°   |